



The product described in this document has not been fully tested to ensure conformance to the requirements outlined below. Therefore, TE Connectivity (TE) makes no representation or warranty, express or implied, that the product will comply with these requirements. Further, TE may change these requirements based on the results of additional testing and evaluation. Contact TE Engineering for further details.

SMC – Receptacle with Ribbon Cable – IDC & Header

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1. SCOPE

1.1. Content

This specification describes the requirements, performance and testing for the double row Insulation Displacement Connector (IDC) system SMC.

The platform is intended for use with flat ribbon cables and has pin counts from 12 to 80 positions.

SMC Female connector with cable outlet 90° in combination with Male connector PCB orientation straight or right-angled.



1.2. General Product Description

This double row Insulation Displacement Connector (IDC) contact system combines the features of high packing density, robust construction and highest functional requirements. Despite its miniaturized design with a grid of 1,27mm, it fulfills all requirements for a contact system suitable for use in an industrial environment and as well in automobiles on a high-performance level.

The electrical contact is made by a rectangle pin with dimension of 0.3mm x 0.42mm. The IDC socket contact has two contact points for electrical connection. The contact normal force is generated by a dual beam contact system.

The IDC contact is inseparably attached to the female housing. The IDC supports a AWG30 flat ribbon cable sizes exclusively.

A primary and secondary locking device (TPA) is not needed for IDC connection.

A Connector Position Assurance (CPA) is not available.

The connector system is unsealed.

1.3. Qualification

When tests are performed for the System, procedures specified in Chapter **Fehler! Verweisquelle konnte nicht gefunden werden.** shall be used.

All tests must be carried out according to the associated inspection plans and drawings.

1.4. Qualification Test Results

The product performs the electrical, mechanical and climatic requirements of Chapter 3.5

2. APPLICABLE DOCUMENTS AND FORMS

The following documents constitute a part of this specification to the extent specified herein. Unless otherwise indicated, the latest edition of the document is applicable.

2.1. TE Documents

- 114-160992: Application Specification (SMC IDC Socket Housing)
- 114-TBD: Application Specification (SMC SMT Male Housing)
- 107-TBD: Product Packaging Specification
- 501-: Qualification Test Report

	Industrial + MIL	Industrial UL	Automotive	Automotive
Specification	IEC60603* EN 60352-2**	UL 1977 (USR) UL/CSA	USCAR2 USCAR21	LV214
Test Report No	501-917e_IND* 501-918e_IND**	File E84703	-	501-3001_AE 501-3002_AE 501-3003_AE

* Connector Qualification

** Ribbon Cable Qualification

2.2. Industry Documents and Standards

- DIN/IEC 60512 Electromechanical components for electrical equipment, basic testing procedures and measuring methods
- DIN EN 60068 Environmental testing
- EN 60352-4 Solderless connections – solderless non-accessible insulation displacement connections; General requirements
- IEC 60603-2 Connectors for frequencies below 3MHz for use with printed boards
- MIL-STD-1344A Military Standard – Test for Electrical Connectors
- UL1977 Component Connectors for Use in Data, Signal, Control and Power Applications (Rev 3: 2007-12)
- LV214 Motor Vehicle Connectors (VW75174:2018-10; VW75174:2010-04)
- IPC/JEDEC J-STD-020 Moisture/Reflow Sensitivity Classification for Non-hermetic Solid State Surface Mount Devices

2.3. Reference Document

- 109-197 Test Specification (TE Test Specification vs EIA and IEC Test Methods)

3. REQUIREMENTS

3.1. Design and Construction

Product shall be of the design, construction, materials and physical dimensions specified on the applicable product drawing.

The product has the following ratings (operating):

	Industrial + MIL	Industrial UL	Automotive	Automotive
Specification	IEC60603	UL 1977** (USR)	USCAR2 USCAR21	LV214
Temperature Class - Au	-40°C to 125°C	(130°C)**	-	-40°C to 125°C
Vibration Class - Sinusoidal - Random - Shock	Performance Category 1 10-2000Hz/ 7,5h/ 20g 30-1050Hz/ 20h/ 3,5g; 1,2g 10 shocks @ 50g/ 11ms	-	-	PG17 S2
Sealing Class IP Class (IEC 60529)	IP00		-	Unsealed
Operating Voltage (U _{RMS})	10VDC*			
Durability Mating Cycles - Au	Performance Category 1 500 cycles	-	-	100 cycles
Current Carrying Capability (AWG30)	-	-	-	1,23A (20-pole) 0,98A (40-pole) 0,91A (80-pole)
Wire Size	0,06mm ² AWG30			
IDC Qualification	DIN EN 60352-4	-	-	LV214*** DIN EN 60352-4
Flammability (Connector HSG Components)	UL94 V0			

* Voltage Rating is in accordance with IEC 60 664-1 (DIN VDE 0110) – corresponding to C&C, CTI and Pollution Degree 2

** Base Material Temperature Rating for Molding Materials (Male/Female)

*** Applicable and Relevant Test Groups

3.2. Materials

Description	Material	Color * with Mechanical Coding	Characteristics
Female housing	LCP reinforced	black	CTI = 175
Cable guide	LCP reinforced	black	CTI = 175
Female IDC contact	Copper Alloy		
Plating connection area	Sn over Ni		
Plating contact area	Au finish		
Male housing (angled)	LCP reinforced	black	CTI = 175
Male contact (angled)	Copper Alloy		
Plating connection area	Sn over Ni		
Plating contact area	Au finish		
Male housing (straight)	LCP reinforced	black	CTI = 175
Male contact (straight)	Copper Alloy		
Plating connection area	Sn over Ni		
Plating contact area	Au finish		

3.3. Ratings

Pin count	Voltage Rating (U _{RMS})	Maximum Current ² (AWG30)	Ambient Temperature ³ for operation	Maximum Operating temperature ⁴
12-80	10 VDC ¹	1.6 at 20 °C 0.9 at 90 °C 0.5 A at 110°C 0.0 A at 125°C	-40 °C to 125 °C Additional restrictions may result from the applied wire.	125 °C with 0 A Additional restrictions may result from the applied wire.

¹ Voltage Rating is in accordance with IEC 60 664-1 (DIN VDE 0110) – corresponding to C&C, CTI and Pollution Degree 2.

² Maximum current for 12-pin connector (type Q male header 90° & type B female receptacle 90°) on Standard one-layer FR4 PCB. For other number of poles the number of poles specific derating curve must be applied.

³ Environmental temperatures wherein the assembly is allowed to operate in.

⁴ Maximum operating temperature - including temperature rise of the contacts by applying an electrical current.

Applicable Wire Flat Ribbon Cable	AWG 30/7Sn (7x0,102 / 0,06mm ²) AWG 30/7Ag (7x0,102 / 0,06mm ²) 

3.4. Quality Assurance Provision

3.4.1. Operation Mode

- Pollution degrees 2 addition: restricted to a non-condensing environment. (IEC 61010-1)
- Overvoltage category 2 (IEC 60664-1)
- Maximum operating altitude 2000 m (IEC 60664-1)
- Condensation: Not permitted
- Icing: Not permitted
- Precipitation, rainfall: Not permitted
- Water (except rainfall): Not permitted
- Moisture: Permitted

3.4.2. IP Protection Class

- IP00 Female housing type P cable outlet 90°

3.4.3. Storage Condition

- According to IEC 60721-3-1 Class 1K4

3.4.4. Technical Cleanliness

- VDA Band 19 / ISO 16232, max. metallic flitter size: 400µm

3.4.5. Soldering and MSL

- IPC/JEDEC J-STD-020
- MSL 1

3.4.6. Test Condition

Unless otherwise specified, all tests shall be performed at ambient environmental conditions.

Temperature	15 – 35 °C
Relative humidity	25 - 75%
Atmospheric pressure	86 – 106 kPa

3.5. Test Requirements and Procedures Summary

Unless otherwise specified, all tests shall be performed at ambient environmental conditions.

Test Coverage:

IEC 60603-2 Connectors for frequencies below 3MHz for use with printed boards - performance level 1

MIL-STD-1344A Military Standard – Test for Electrical Connectors

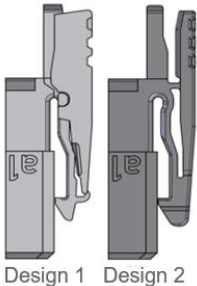
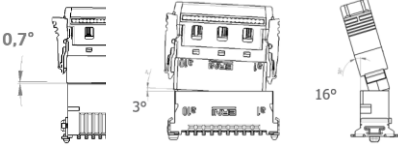
LV214 Motor vehicles connectors - according to the qualification matrix LV214-1.

TEST DESCRIPTION	REQUIREMENT	PROCEDURE
	VISUAL / GENERAL	
LV214 TG0 / TG1 Initial examination of product / Visual inspection Dimensions	Meets requirements of product drawing (drawing conformity)	VW75174:2018-10 E0.1 / DIN EN 60512-1-1 E1.1 / DIN EN 60512-1-2
LV214 TG1 Dimension of processed components	Meets requirements of product drawing (drawing conformity)	VW75174:2018-10 E1.2 / DIN EN 60512-1-2
DIN EN 60352-4 Solderless connections - IDC		DIN EN 60352-2 ZP1

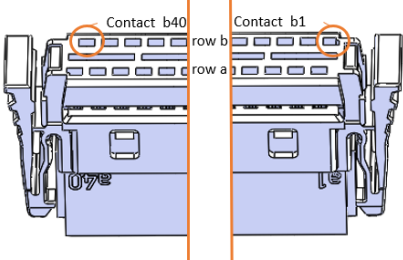
	ELECTRICAL	
LV214 – TG0 Inspection of as-received condition Volume resistance Insulation resistance	$R < 50\text{m}\Omega$ (AWG30) $R_{\text{ins}} > 100\text{M}\Omega$ at $U=500\text{V}$, $t=60\text{s}$	VW75174:2018-10 P 0.2 / DIN EN 60512-2-1 P 0.3 / DIN EN 60512-3-1
DIN EN 60603-2 – P3 Contact resistance	$R \leq 25\text{m}\Omega$	DIN EN 60512-2-1 MIL STD-1344 A 3002.1
DIN EN 60603-2 – P4 Insulation resistance	$R \geq 10^{10} \Omega$	DIN EN 60512-3-1 MIL STD-1344 A 3003.1
DIN EN 60603-2 – P5 Voltage proof	$U_{\text{test}} = 500\text{V}_{\text{eff}}$ (contact/contact)	DIN EN 60512-4-1 MIL STD-1344 A 3001.1
LV214 – TG12 Current heating, derating Derating without contact housing	Documentation and Determination Nominal current I_{nom} $I_{\text{nominal}} = 1,23\text{A}$ (20-pole) $I_{\text{nominal}} = 0,98\text{A}$ (40-pole) $I_{\text{nominal}} = 0,91\text{A}$ (80-pole)	VW75174:2018-10 P 12.2 n.a. Contact parts are inseparably attached to the housing. It is not possible to assemble the wire without a housing. For nominal current ($I_{\text{nom}}/I_{\text{test}}$) a current I [A] from TG13 derating curve at 80°C ambient temperature is used.
LV214 – TG13 Influence of the contact housing on the derating Derating with contact housing	See Chapter 4.1 Derating - Number of Poles Specific	VW75174:2018-10 P13.2
LV214 – TG14 Thermal time constant (current overtemperature at n times the nominal current) Thermal time constant P 0.1 Visual inspection	See Chapter 4.3 Thermal Time Constant – LV214 TG14 No defects were detected. No changes on the contact surfaces were detected.	VW75174:2018-10 P 14.1 The nominal current I_{nom} is picked from TG13 (at 80°C ambient temperature) $I_{\text{nominal}} = 1,23\text{A}$ (20-pole) $I_{\text{nominal}} = 0,98\text{A}$ (40-pole) $I_{\text{nominal}} = 0,91\text{A}$ (80-pole) Wire Size: AWG30 T_{max} : 125°C

DIN EN 60603-2 – Test Batch DP		
Gauge retention force	$F_{\text{contact retention}} \geq 0,1\text{N}$ (per contact)	DP0 / DIN EN 60512-16-5
Mechanical operation	Carry out	DP1 / DIN EN 60512-9-1 MIL STD-1344 A 2016 $V = \leq 10\text{mm/s}$ Rest period: $\leq 30\text{s}$ (not inserted) No of cycles: 250
Electrical load and temperature		DP2 / DIN EN 60512-9-2 MIL STD-1344 A 1005 $T = 125^{\circ}\text{C}$ $I = [\text{A}]$ not applied $t = 1000\text{h}$
Contact resistance	$R \leq 25\text{m}\Omega$	DP3 / DIN EN 60512-2-1 MIL STD-1344 A 3002.1
Gauge retention force	$F_{\text{contact retention}} \geq 0,1\text{N}$ (per contact)	DP0.1 / DIN EN 60512-16-5
Voltage proof	$U_{\text{test}} = 500V_{\text{eff}}$ (contact/contact)	DP4 / DIN EN 60512-4-1 MIL STD-1344 A 3001.1
Visual examination	No faults	DP8 / DIN EN 60512-1-1

	MECHANICAL	
LV214 – TG4		
Contact overlap		VW75174:2018-10
Contact overlap	Contact overlap 2.24mm Clearance 0.78mm	P 4.1 CAD determined
LV214 – TG6		
Interaction between contact and contact housing		VW75174:2018-10
Function of the primary locking device/latch play	n.a., contact parts are inseparably pre-assembled in the housing (state of delivery)	P 6.2
Function of the secondary locking device/latch play		P 6.3
Actuation forces for the secondary locking device	n.a. IDC connector has no secondary locking	P 6.4
Drop test	while drop test the pre-latched parts remain in pre-latched position - transport of unequipped contact housings assembled parts stay assembled - transport of equipped contact housings	L 6.1

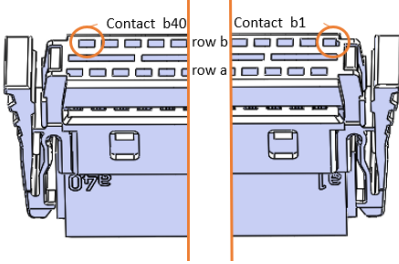
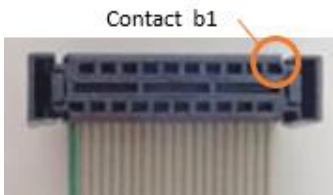
LV214 – TG7 Handling and functional reliability of the contact housings Distinctiveness of the unequipped contact housings (keying/polarization) Holding force of the contact housing latching/locking CPA function check Insertion force or actuation force for insertion and extraction aids	$F_{\text{keying}} \geq 50 \text{ N}$ (0,5mm blade size) $F_{\text{holding}} > 60 \text{ N}$ (12 to 80-pin) Design 2 $F_{\text{holding}} > 20 \text{ N}$ (12 to 80-pin) Design 1  Design 1 Design 2 n.a. The connector system has no CPA feature $F_{\text{insertion}} < 75 \text{ N}$ (typical <30N for 80-pole Design 2)	VW75174:2018-10 P 7.1 / DIN EN 60512-13-5 P 7.2 / DIN EN 60512-15-6 P 7.3 P 7.4
LV214 – TG8 Insertion and holding forces of the contact parts in the contact housing	n.a., contact parts are inseparably pre-assembled in the housing (state of delivery)	VW75174:2018-10
LV214 – TG9 Pin insertion angle / misuse-proofing (scoop-proofing) Scoop proof testing of contact housing	SMC IDC do not meet the requirement for scoop-proofing. Maximum allowed mating angle:  80-pole & 20-pole	VW75174:2018-10 P 9.3 CAD determined

LV214 – TG10 Contacts: conductor pull-out strength Conductor pull-out strength (only in connection with crimp) Pull-out force from the IDC (only in connection with IDC)	n.a. $F_{\text{pull-out}} > 50\text{N}$ (AWG30 ribbon cable)	VW75174:2018-10 P 10.1 P 10.2
LV214 – TG11 Contacts: insertion and extraction forces, number of mating cycles Insertion and removal force Number of mating cycles	$F_{\text{insert/extract}} < 25\%$ Change of insertion / extraction force before and after load AU: 100 mating cycles	VW75174:2018-10 P 11.1 L11.1
DIN EN 60603-2 – Test AP - AP1 Gauge retention force	$F_{\text{contact retention}} \geq 0,1\text{N}$ (per contact)	DIN EN 60512-16-5
LV214 – TG17 (12 - 68-pole) Dynamic load Volume resistance Volume resistance – continuous monitoring during mechanical loads L17.1 & L17.2 Dynamic load, sinusoidal Dynamic load, broadband noise Shock durability testing	$R_{\text{before/after test}} \leq 50\text{ m}\Omega$ No current interruption ($> 1\text{ }\mu\text{s}$ / $> 7\text{ }\Omega$)	VW75174:2018-10 P 0.2 / DIN EN 60512-2-1 After deduction of the cable resistance, the final contact resistances $P0.2 \leq 50\text{ m}\Omega$ P 14.0 Test is performed according to Severity level 2 (body – sealed) L 17.1 / DIN EN 600068-2-6 No sine wave load at S2 L 17.2 / DIN EN 60068-2-64 $a_{\text{RMS}} 27.8\text{m/s}^2$; $t = 20\text{h}$ per axis L 17.3 / DIN EN 60068-2-27 $a = 30\text{g}$; $t = 6\text{ms}$; shocks 6000

LV214 – TG17 (80-pole) Dynamic load Volume resistance Volume resistance – continuous monitoring during mechanical loads L17.1 & L17.2	$R_{\text{before/after test}} \leq 50 \text{ m}\Omega$ Outmost contacts show a slightly increased contact resistance, result is below the limit of $\leq 50 \text{ m}\Omega$, Deviate from that applies: Contact b₁ $R_{\text{after test}} < 7\Omega$ No current interruption ($> 1 \mu\text{s}$ / $> 7 \Omega$) 	VW75174:2018-10 P 0.2 / DIN EN 60512-2-1 After deduction of the cable resistance, the final contact resistances $P0.2 \leq 72 \text{ m}\Omega$ P 14.0 Test is performed according to Severity level 2 (body – sealed)
DIN EN 60603-2 – Test Batch AP Gauge retention force Total insertion and withdrawal force Solderability Voltage proof Vibration sinusoidal Monitoring contact break Shock Monitoring contact break Rapid change of temperature Insulation resistance Voltage proof	$F_{\text{contact retention}} \geq 0,1\text{N}$ (per contact) $F_{\text{I\&W}} \leq 26\text{N}$ (50-pole) $F_{\text{I\&W}} \leq 40\text{N}$ (80-pole) Not applicable $U_{\text{test}} = 500V_{\text{eff}}$ (contact/contact) Contact break $\leq 1 \mu\text{s}$ Contact break $\leq 1 \mu\text{s}$ Carry out $R \geq 10^{10} \Omega$ $U_{\text{test}} = 500V_{\text{eff}}$ (contact/contact)	AP1 / DIN EN 60512-16-5 AP2 / DIN EN 60512-13-2 MIL STD-1344 A 2013.1 AP3 / DIN EN 60512-12-1 AP4 / DIN EN 60512-4-1 MIL STD-1344 A 3001.1 AP6 / DIN EN 60512-6-3 MIL STD-1344 A 3004.1 $a = 1,5\text{mm}$ or 20g $f = 10 - 2000\text{Hz}$ $t = 7,5\text{h}$ No of cycles = 10 AP7 / DIN EN 60512-6-3 MIL STD-1344 A 1003.1 $a = 490\text{m/s}$ (50g) half sine: $3,43\text{m/s}^2$ $t = 11\text{ms}$ No of cycles: 10 shocks/axis AP9 / DIN EN 60512-11-4 MIL STD-1344 A 1003.1 $T = -55^\circ\text{C}$ to $+125^\circ\text{C}$ $t = 30 \text{ min}$ No of cycles = 5 AP10 / DIN EN 60512-3-1 MIL STD-1344 A 3003.1 AP11 / DIN EN 60512-4-1 MIL STD-1344 A 3001.1

Visual examination	No faults	AP12 / DIN EN 60512-1-1
Climatic sequence	Carry out	AP13 / DIN EN 60512-11-1
Dry heat		13.1 / DIN EN 60512-11-9 T = +125°C t = 16h
Damp heat, cyclical		13.2 / DIN EN 60512-11-13 variant 1
Cycle 1		T = 55°C
Cold		13.3 / DIN EN 60512-11-10 T = -55°C
Damp heat, cyclical		13.5 / DIN EN 60512-11-1
Cycle 2 - 6		T = 55°C
Insulation resistance	$R \geq 10^{10} \Omega$	AP14 / DIN EN 60512-3-1 MIL STD-1344 A 3003.1
Contact resistance	$R \leq 25m\Omega$	AP15 / DIN EN 60512-2-1 MIL STD-1344 A 3002.1
Voltage proof	$U_{test} = 500V_{eff}$ (contact/contact)	AP16 / DIN EN 60512-4-1 MIL STD-1344 A 3001.1
Total insertion and withdrawal force	$F_{I\&W} \leq 26N$ (50-pole) $F_{I\&W} \leq 40N$ (80-pole)	AP17 / DIN EN 60512-13-2 MIL STD-1344 A 2013.1
Visual examination	No faults	AP18 / DIN EN 60512-1-1

	ENVIRONMENTAL	
LV214 TG5 Mechanical and thermal relaxation behavior		VW75174:2010-04
Contact normal force		E5.2 (retention force with gauge)
Unused	$\geq 0,1 N$	E5.2 (retention force with gauge)
After B5.3 aging in dry heat	$\geq 0,1 N$	B5.3 / DIN EN 60068-2-2 / Test B 1000 h @ 125°C
LV214 – TG15 Electrical stress test		VW75174:2018-10
Volume resistance	$R_{before/after\ test} \leq 50\ m\Omega$ (AWG30)	P 0.2 / DIN EN 60512-2-1
Derating (before/after test)	$I_{nominal\ change} < 20\%$	P12.2 / DIN EN 60512-5-2 with housing $I_{nom} = 2,98A / 2,8A$ (20-pole) 3,0A / 3,0A (40-pole) 3,3A / 3,3A (80-pole)
Temperature/ current cycle endurance test:		B15.2 / 60 cycl. -40°C/T ₀ =125°C $I_{test} = 3,7A$ (20-pole); 3,0A (40-pole) 3,8A (80-pole)

Humidity heat, cyclic: Temperature/ current cycle endurance test:		B15.3 / DIN EN 60068-2-30 21x1day @ 25°C/55°C @ 95%RH B15.2
LV214 – TG18A Coastal climate load Volume resistance Salt spray, cyclic	$R_{\text{before/after test}} \leq 50 \text{ m}\Omega$	VW75174:2018-10 P 0.2 / DIN EN 60512-2-1 B 18.2 / DIN EN 60068-2-52 Severity 3
LV214 – PG19 Environmental simulation Volume resistance Temperature shock Temperature change Aging in dry heat Industrial climate (multi-component climate)	Connector 12-pole to 40-pole $R_{\text{before/after test}} \leq 50 \text{ m}\Omega$ Connector 50-pole to 80-pole $R_{\text{before/after test}} \leq 50 \text{ m}\Omega$ Deviate from that applies: Contact resistance of contact b_1, a_1 & b_n, a_n increases after temperature load. Contact b_1, a_1, b_n, a_n $R_{\text{after test}} < 7 \Omega$   80-pin n-contact for: 50-pin: $a_n = a_{25}$; $b_n = b_{25}$ 68-pin: $a_n = a_{34}$; $b_n = b_{34}$ 80-pin: $a_n = a_{40}$; $b_n = b_{40}$	VW75174:2018-10 P 0.2 / DIN EN 60512-2-1 L 19.1 / DIN EN 60068-2-14, Test Na Duration: 144 cycles (72h) Temperature: -40 °C/130°C (a 15min; $\updownarrow$10s) L 19.2 / DIN EN 60068-2-14, Test Nb Duration: 20 cycles Temperature: -40 °C/130°C (a 3h; $\updownarrow$ 2h) L 19.3 / DIN EN 60068-2-2, Test B Duration: 120 h Temperature: 130°C L 19.4 / DIN EN 60512-11-7 Duration: 21d SO₂, 0,2 ppm H₂S, 0,01 ppm NO₂, 0,2 ppm Cl₂ 0,01 ppm Temperature: 25°C Humidity: 75% RH Flow rate: 1 m³/h

Damp heat, cyclic		L 19.5 / DIN EN 60068-2-30, variant 2 Duration: 10 cycles of 24h each $T_u = 25\text{ }^{\circ}\text{C}$, $T_o = 55\text{ }^{\circ}\text{C}$, RH 95%
Dynamic load, Broadband noise		L 19.6 / DIN EN 60068-2-64 $a_{\text{RMS}} 13.9\text{m/s}^2$; $t = 6\text{h}$ per axis
Mechanical shock testing (individual shocks)		L 19.7 / DIN EN 60068-2-27 $a = 30\text{g}$; $t = 6\text{ms}$; shocks 50 per axis
LV214 – PG20 Climate load of the housing	Conformity to TestGroup specific functional requirements.	VW75174:2018-10
Aging in dry heat		L 20.1 / DIN EN 60068-2-2, Test B Duration: 120 h Temperature: 125°C
Aging in damp heat		L 20.2 / DIN EN 60068-2-30 Duration: 10 days Temperature: 40°C Relative humidity: 95 %
Low-temperature aging		L 20.3 / DIN EN 60068-2-1 Duration: 48 h Temperature: -40°C
Extracting and inserting at -20°C		L 20.4
Aging in dry heat		L 20.5 / DIN EN 60068-2-2, Test B Duration: 48 h Temperature: 80°C
Drop test in the unplugged state		L 6.1 / VW75174:2018-10
LV214 – TG21 Long-term temperature aging	Conformity to TestGroup specific functional requirements $R_{\text{before/after test}} \leq 50\text{ m}\Omega$	VW75174:2018-10
Volume resistance		P 0.2 / DIN EN 60512-2-1
Long-term aging in dry heat		L 21.1 / DIN EN 60068-2-2, Test B Duration: 1000 h Temperature: 130°C Subsequent aging: 48h at RT
B 6.1 Drop test		VW75174:2018-10

LV214 – TG22A Chemical resistance Insulation resistance Resistance to agents	Conformity to TestGroup specific material & functional requirements R_{ins} before/after test > 100M Ω at U=500V, t=60s	VW75174:2018-10 P 0.3 / DIN EN 60512-3-1 L 22.1A / VW75174:2018-10 Appendix E.1 media list Duration: 48h Temperature: media specific
DIN EN 60603-2 – Test Batch BP Gauge retention force Mechanical operation 1st half Industrial atmosphere Contact resistance Mechanical operation 2nd half Insulation resistance Voltage proof Gauge retention force Visual examination	$F_{contact\ retention} \geq 0,1N$ (per contact) Carry out Carry out $R \leq 25m\Omega$ Carry out $R \geq 10^{10} \Omega$ $U_{test} = 500V_{eff}$ (contact/contact) $F_{contact\ retention} \geq 0,1N$ (per contact) No faults	BP1 / DIN EN 60512-16-5 BP2 / DIN EN 60512-9-1 MIL STD-1344 A 2016 $V = \leq 10mm/s$ Rest period: $\leq 30s$ (not inserted) No of cycles: 250 BP3.2 / DIN EN 60512-11-7 Test climate: 25°C/ 75% RH Gas concentration: mixed flowing gas 0,5ppm SO ₂ + 0,1ppm H ₂ S t = 10 days one half of specimen inserted; the other half not inserted. BP4 / DIN EN 60512-2-1 MIL STD-1344 A 3002.1 BP5 / DIN EN 60512-9-1 MIL STD-1344 A 2016 $V = \leq 10mm/s$ Rest period: $\leq 30s$ (not inserted) No of cycles: 250 BP6 / DIN EN 60512-3-1 MIL STD-1344 A 3003.1 BP7 / DIN EN 60512-4-1 MIL STD-1344 A 3001.1 BP9 / DIN EN 60512-16-5 BP10 / DIN EN 60512-1-1
DIN EN 60603-2 – Test Batch CP Damp heat, steady		CP1 / DIN EN 60512-11-3 MIL STD-1344 A 1002.1 Polarization voltage: not applied Test climate: 40°C/ 93% RH t = 56 days

Insulation resistance	$R \geq 10^{10} \Omega$	CP2 / DIN EN 60512-3-1 MIL STD-1344 A 3003.1
Contact resistance	$R \leq 25\text{m}\Omega$	CP3 / DIN EN 60512-2-1 MIL STD-1344 A 3002.1
Voltage proof	$U_{\text{test}} = 500V_{\text{eff}}$ (contact/contact)	CP4 / DIN EN 60512-4-1 MIL STD-1344 A 3001.1
Visual examination	No faults	CP5 / DIN EN 60512-1-1

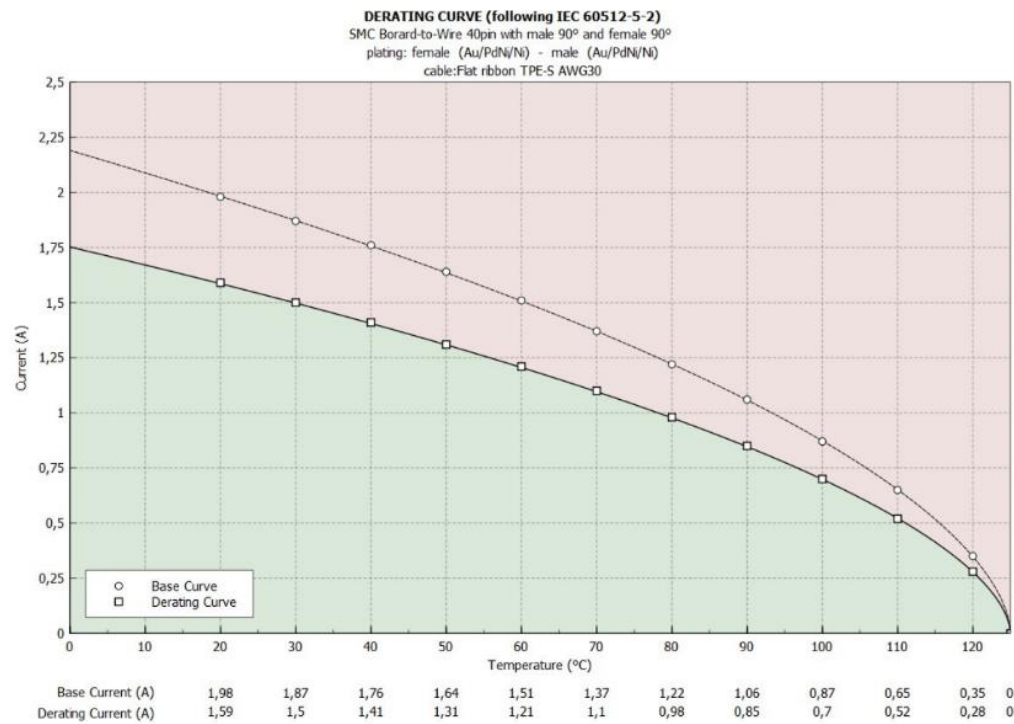
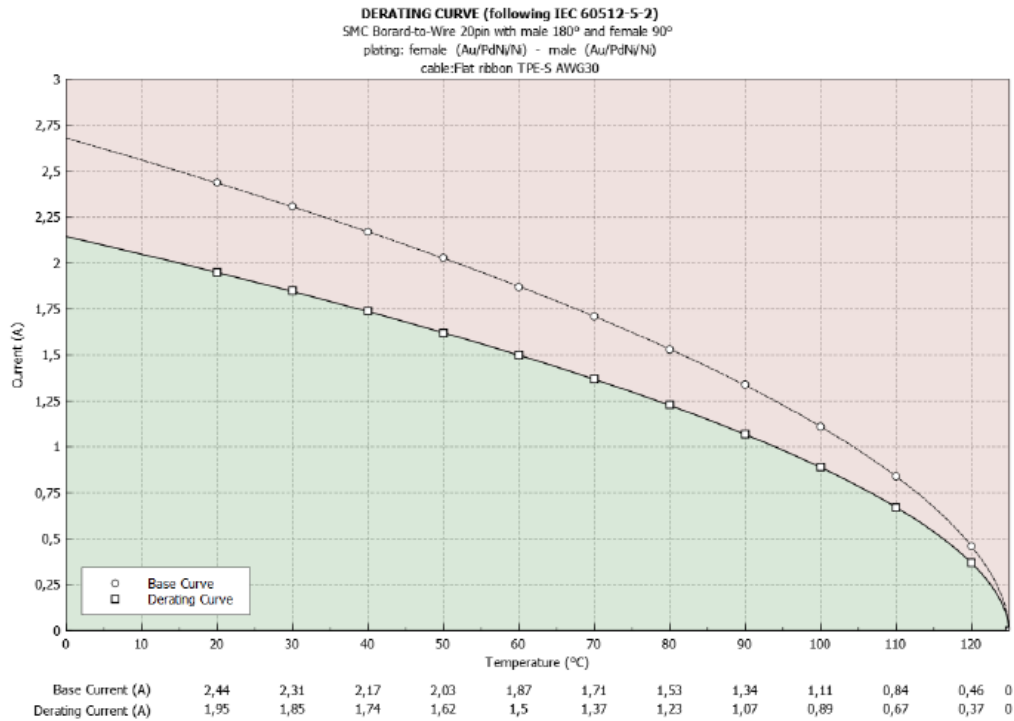
3.6. Product Qualification and Requalification Test Sequences

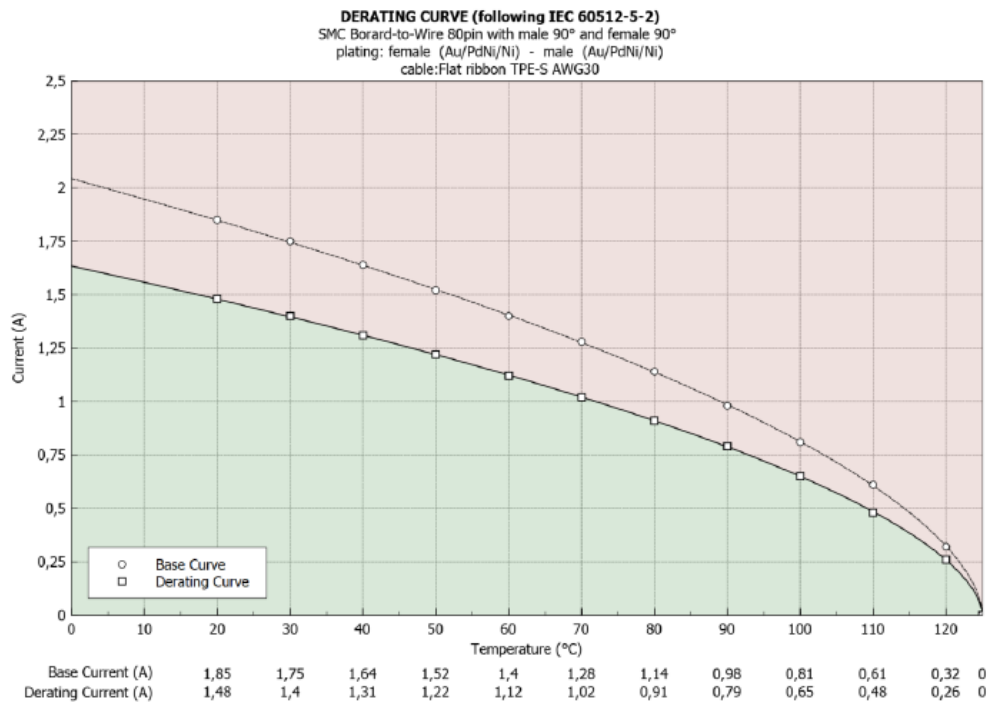
For the product qualification all test groups and sequences are carried out in accordance with DIN EN 60603-2 and LV214 as per Chapter 3.5.

A product requalification is performed annually with at least one selected connector type of a product family. Every requalification includes tests to ensure the functionality and dimensional accuracy of the products. Unless otherwise specified by TE, a requalification test will be carried out at the same revision level as specified in Chapter 3.5

4. APPENDIX

4.1. Derating - Number of Poles Specific





4.2. Resistance Limits – LV214 Appendix Table D.1

Conductor cross section in mm ² /contact size in mm	Group 1						Group 2					Group 3	
	0.13	0.22	0.35	0.5	0.75	1	1.5	2.5	4	6	10	16	> 16
0.5	50	40	30	-	-	-	-	-	-	-	-	-	-
0.63	30	30	15	15	15	-	-	-	-	-	-	-	-
1.2	20	20	15	15	15	15	10	-	-	-	-	-	-
1.5	15	15	15	15	15	15	10	10	-	-	-	-	-
2.8	15	15	15	15	15	10	10	10	5	-	-	-	-
4.8 – 6.3	10	10	10	8	8	8	5	5	3	3	2	-	-
8	-	-	-	-	-	-	-	3	3	3	2	2	-
9.5 – 12	-	-	-	-	-	-	-	-	3	2	2	1	1

4.3. Thermal Time Constant – LV214 TG14

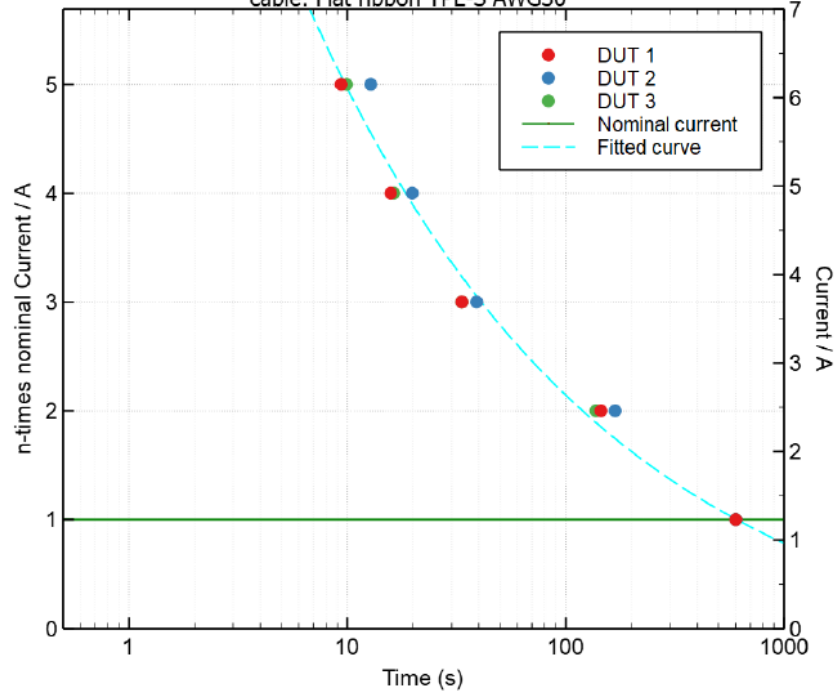
TG14 Thermal time constant (following VW 75174 :2018-10)

SMC Board-to-Wire 20pin with male 180° and female 90°

plating: male (Au / PdNi / Ni)

plating: female (Au / PdNi / Ni)

cable: Flat ribbon TPE-S AWG30



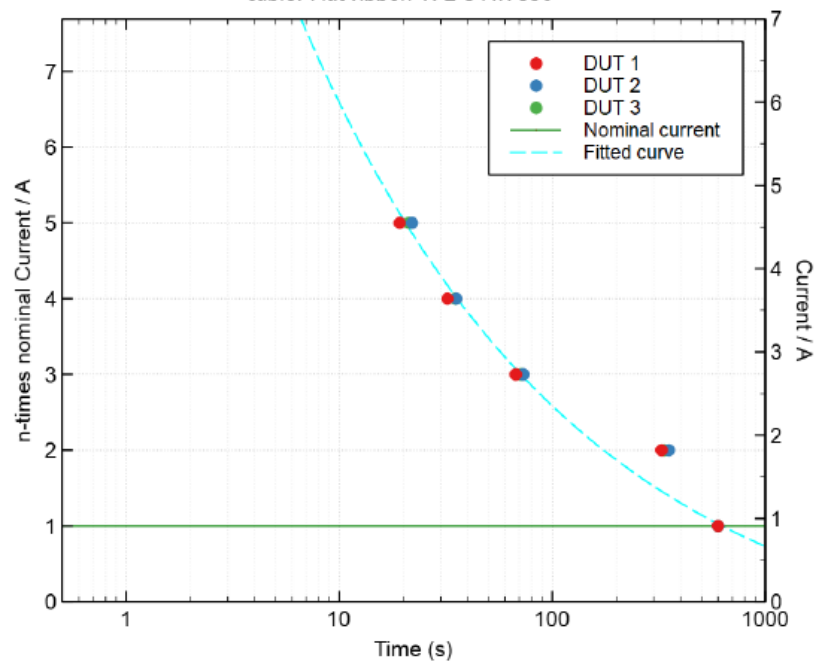
TG14 Thermal time constant (following VW 75174 :2018-10)

SMC Board-to-Wire 80pin with male 90° and female 90°

plating: male (Au / PdNi / Ni)

plating: female (Au / PdNi / Ni)

cable: Flat ribbon TPE-S AWG30



4.4. Dynamic Load – LV214 TG17

Test	Severity	Description	TC	Wide-Band Random Vibration with TC		Sinusiodal with TC	Shock
PG17	2	"Body" sealed	-40°C / +120°C	20 h per Axis; Amplitude (RMS) of acceleration: 27,8 m/s ²		No sine wave	a a) = 30 g t b) = 6 ms Sinusiodal half-wave No of Shocks: 6 000
				Hz	(m/s ²)/Hz		
				10	20		
				55	6,5		
				180	0,25		
				300	0,25		
				360	0,14		
				1 000	0,14		

4.5. Shaker Table Mounting – LV214 Appendix B

See figure B.1 and figure B.2

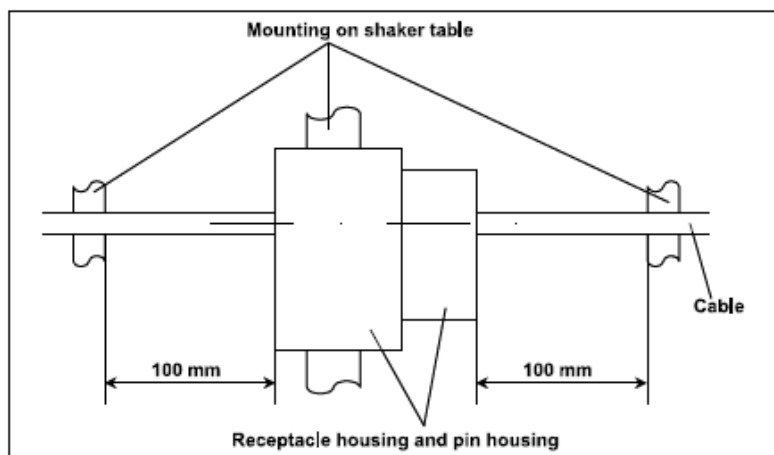


Figure B.1 – Mounting on shaker table, coupling

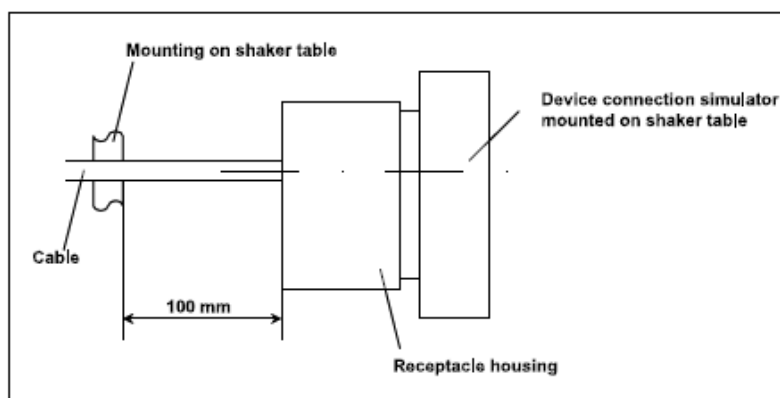
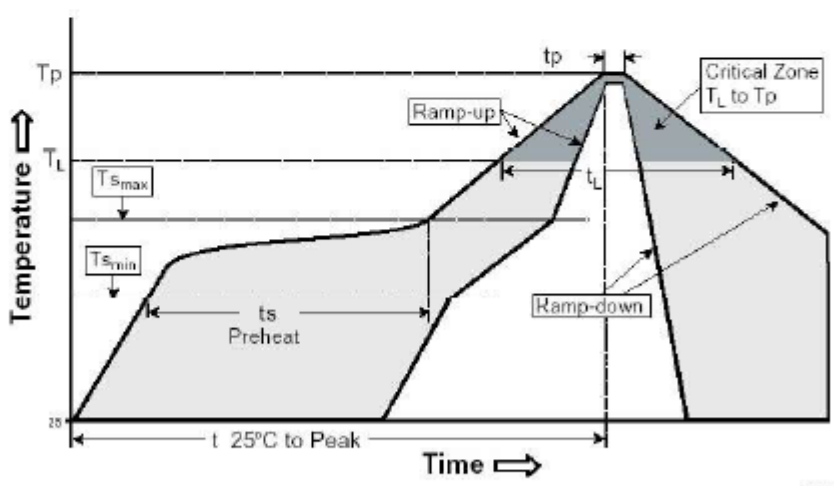
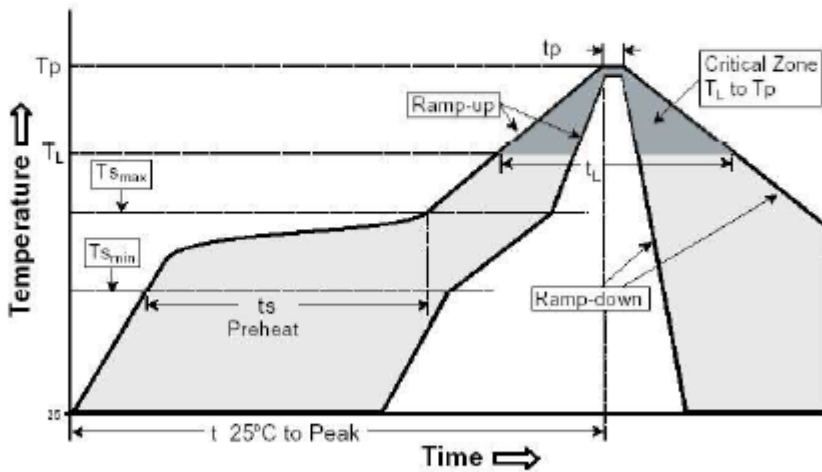


Figure B.2 – Mounting on shaker table, device connection

4.6. Solderability – SMT Reflow Solderability

Test	Test, Measurements, Results														
ZP 3	SMT/ THR Reflow solderability IEC 60068-2-58 Ed. 3 (FDIS) Solder paste: SnAgCu/ melting point: 217°C Reflow profile to distinguish solder ability <table border="1"> <thead> <tr> <th>Profile Feature</th><th>Pb-Free Assembly</th></tr> </thead> <tbody> <tr> <td>Average Ramp-Up Rate (T_{smax} to T_p)</td><td>3°C/ second max.</td></tr> <tr> <td>Preheat – Temperature Min (T_{smin}) – Temperature Max (T_{smax}) – Time (t_{smin} to t_{smax})</td><td>150 ± 5°C 180 ± 5°C 60-120 seconds</td></tr> <tr> <td>Time maintained above: – Temperature (T_L) – Time (t_L)</td><td>225°C 20 ± 5seconds</td></tr> <tr> <td>Peak/Classification Temperature (T_p)</td><td>235°C (+0/-5°C)</td></tr> <tr> <td>Time within 5 °C of actual Peak Temperature (t_p)</td><td>10 seconds</td></tr> <tr> <td>Ramp-Down Rate</td><td>6 °C/second max.</td></tr> </tbody> </table>  Result: Carried out Visual Inspection IEC 60 512 test 1 a (Bellcore GR-1217-Core Abs. 5.1.1) Result: The connections were soldered without failures - passed!	Profile Feature	Pb-Free Assembly	Average Ramp-Up Rate (T_{smax} to T_p)	3°C/ second max.	Preheat – Temperature Min (T_{smin}) – Temperature Max (T_{smax}) – Time (t_{smin} to t_{smax})	150 ± 5°C 180 ± 5°C 60-120 seconds	Time maintained above: – Temperature (T_L) – Time (t_L)	225°C 20 ± 5seconds	Peak/Classification Temperature (T_p)	235°C (+0/-5°C)	Time within 5 °C of actual Peak Temperature (t_p)	10 seconds	Ramp-Down Rate	6 °C/second max.
Profile Feature	Pb-Free Assembly														
Average Ramp-Up Rate (T_{smax} to T_p)	3°C/ second max.														
Preheat – Temperature Min (T_{smin}) – Temperature Max (T_{smax}) – Time (t_{smin} to t_{smax})	150 ± 5°C 180 ± 5°C 60-120 seconds														
Time maintained above: – Temperature (T_L) – Time (t_L)	225°C 20 ± 5seconds														
Peak/Classification Temperature (T_p)	235°C (+0/-5°C)														
Time within 5 °C of actual Peak Temperature (t_p)	10 seconds														
Ramp-Down Rate	6 °C/second max.														

4.7. Solderability – SMT Reflow Resistance to Soldering Heat

Test	Test, Measurements, Results																
ZP 4	SMT/ THR Reflow resistance to soldering heat IPC/ JEDEC J-STD-020C Number of cycles: 3 Reflow profile to distinguish resistance to soldering heat <table border="1"> <thead> <tr> <th>Profile Feature</th><th>Pb-Free Assembly</th></tr> </thead> <tbody> <tr> <td>Average Ramp-Up Rate (T_{smax} to T_p)</td><td>3°C/ second max.</td></tr> <tr> <td>Preheat – Temperature Min (T_{smin}) – Temperature Max (T_{smax}) – Time (t_{smin} to t_{smax})</td><td>150°C 200°C 60-180 seconds</td></tr> <tr> <td>Time maintained above: – Temperature (T_L) – Time (t_L)</td><td>217°C 60-150 seconds</td></tr> <tr> <td>Peak/Classification Temperature (T_p)</td><td>260°C (+0/-5°C)</td></tr> <tr> <td>Time within 5 °C of actual Peak Temperature (t_p)</td><td>20-40 seconds</td></tr> <tr> <td>Ramp-Down Rate</td><td>6°C/second max.</td></tr> <tr> <td>Time 25 °C to Peak Temperature</td><td>8 minutes max</td></tr> </tbody> </table>  Result: Carried out! Visual Inspection IEC 60 512 test1 a (Bellcore GR-1217-Core Abs, 5,1,1) Result: Passed! There were no deformations and failures on the housing and the contacts!	Profile Feature	Pb-Free Assembly	Average Ramp-Up Rate (T_{smax} to T_p)	3°C/ second max.	Preheat – Temperature Min (T_{smin}) – Temperature Max (T_{smax}) – Time (t_{smin} to t_{smax})	150°C 200°C 60-180 seconds	Time maintained above: – Temperature (T_L) – Time (t_L)	217°C 60-150 seconds	Peak/Classification Temperature (T_p)	260°C (+0/-5°C)	Time within 5 °C of actual Peak Temperature (t_p)	20-40 seconds	Ramp-Down Rate	6°C/second max.	Time 25 °C to Peak Temperature	8 minutes max
Profile Feature	Pb-Free Assembly																
Average Ramp-Up Rate (T_{smax} to T_p)	3°C/ second max.																
Preheat – Temperature Min (T_{smin}) – Temperature Max (T_{smax}) – Time (t_{smin} to t_{smax})	150°C 200°C 60-180 seconds																
Time maintained above: – Temperature (T_L) – Time (t_L)	217°C 60-150 seconds																
Peak/Classification Temperature (T_p)	260°C (+0/-5°C)																
Time within 5 °C of actual Peak Temperature (t_p)	20-40 seconds																
Ramp-Down Rate	6°C/second max.																
Time 25 °C to Peak Temperature	8 minutes max																

5. REVISION HISTORY TABLE

REV	Revision record	Drawn	Checked	Approved	Date
A	Published to PDM Link & DSD	T. Lengenfelder	T. Oberschelp	S. Kaminski	23 Apr 2024
A2	Solderability - Profiles	T. Lengenfelder	J. Koch	S. Kaminski	08 Aug 2024